SFH 4770S A01

SYNIOS® P2720

IR SYNIOS P2720 (850 nm) - 120°









Applications

- Driver Monitoring / Seat Occupancy Detection
- Eye Tracking

- Gesture Recognition
- Safety and Security, CCTV

Features:

- Package: clear silicone
- Corrosion Robustness Class: 3B
- Qualifications: The product qualification test plan is based on the guidelines of AEC-Q101-REV-C,
 Stress Test Qualification for Automotive Grade Discrete Semiconductors.
- ESD: 2 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)
- IR lightsource with high efficiency
- Double stack emitter
- Low thermal resistance (Max. 9 K/W)
- Centroid wavelength 850 nm

Ordering Information

Туре	Total radiant flux $^{1)2)}$ $I_{F} = 1000 \text{ mA; } t_{p} = 10 \text{ ms}$ Φ_{e}	Total radiant flux ¹⁾ typ. $I_F = 1000 \text{ mA}$; $t_p = 10 \text{ ms}$ Φ_e	Ordering Code
SFH 4770S A01	900 1400 mW	1,140 mW	Q65112A0523



Maximum Ratings

T_A = 25 °C

Parameter	Symbol		Values
Operating temperature	T _{op}	min.	-40 °C
	ор	max.	125 °C
Storage temperature	T _{stg}	min.	-40 °C
	Sig	max.	125 °C
Junction temperature	T _j	max.	145 °C
Forward current	I _F	max.	1500 mA
Surge current	I _{FSM}	max.	5 A
$t_p \le 300 \mu\text{s}; D = 0.005$			
Reverse current 3)	I _R	max.	200 mA
Power consumption	P _{tot}	max.	5.5 W
ESD withstand voltage	V _{ESD}	max.	2 kV
acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)			

For the forward current and power consumption please see "maximum permissible forward current" diagram



Characteristics

 $I_{\scriptscriptstyle F}$ = 1000 mA; $t_{\scriptscriptstyle p}$ = 10 ms; $T_{\scriptscriptstyle A}$ = 25 °C

Parameter	Symbol	Values	
Peak wavelength	λ_{peak}	typ.	860 nm
Centroid wavelength	$\lambda_{ ext{centroid}}$	typ.	850 nm
Spectral bandwidth at 50% I _{rel,max} (FWHM)	Δλ	typ.	30 nm
Half angle	φ	typ.	60 °
Dimensions of active chip area	LxW	typ.	1 x 1 mm x mm
Rise time (10% / 90%) $I_F = 5 \text{ A}; R_L = 50 \Omega$	t,	typ.	10 ns
Fall time (10% / 90%) $I_F = 5 \text{ A}; R_L = 50 \Omega$	t _f	typ.	15 ns
Forward voltage 4)	V_{F}	min. typ. max.	2.8 V 2.95 V 3.3 V
Forward voltage $^{4)}$ I _F = 1.5 A; t _p = 100 µs	V_{F}	min. typ. max.	2.9 V 3.05 V 3.55 V
Forward voltage $^{4)}$ I _F = 5 A; t _p = 100 µs	V_{F}	min. typ. max.	3.2 V 3.5 V 4.4 V
Reverse voltage ³⁾ I _R = 20 mA	V_R	max.	1.2 V
Reverse voltage (ESD device) 3)	$V_{R ESD}$	min.	5 V
Radiant intensity 5)	l _e	typ.	350 mW/sr
Radiant intensity ⁵⁾ $I_F = 1.5 \text{ A}; t_p = 100 \mu\text{s}$	l _e	typ.	530 mW/sr
Total radiant flux ¹⁾ $I_F = 1.5 \text{ A}; t_p = 100 \mu\text{s}$	Фе	typ.	1700 mW
Temperature coefficient of voltage	TC_v	typ.	-2 mV / K
Temperature coefficient of wavelength	TC _λ	typ.	0.3 nm / K
Thermal resistance junction solder point real ⁶⁾	$R_{thJSreal}$	typ. max.	6.0 K / W 9.0 K / W



Brightness Groups

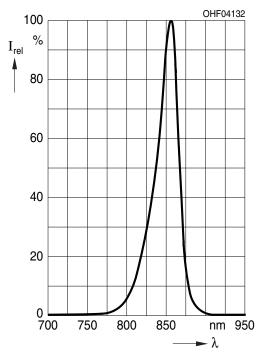
T_A = 25 °C

Group	Total radiant flux $^{1)2)}$ $I_F = 1000$ mA; $t_p = 10$ ms min. Φ_e	Total radiant flux $^{1/2)}$ I _F = 1000 mA; t _p = 10 ms max. Φ_e
EB	900 mW	1120 mW
FA	1120 mW	1400 mW

Only one group in one packing unit (variation lower 1.6:1).

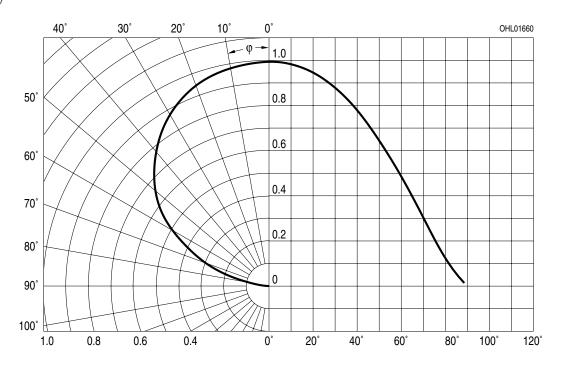
Relative Spectral Emission 7), 8)

 $I_{e,rel} = f(\lambda); I_F = 1000 \text{ mA}; t_p = 10 \text{ ms}$



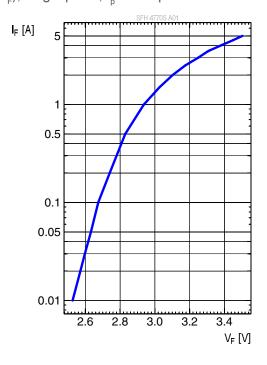
Radiation Characteristics 7), 8)

$$I_{e,rel} = f(\phi)$$



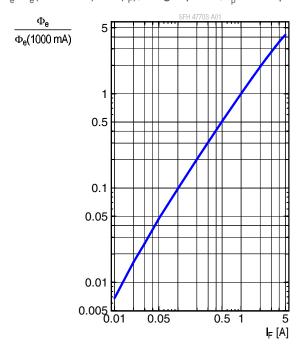
Forward current 7), 8)

 $I_F = f(V_F)$; single pulse; $t_D = 100 \mu s$



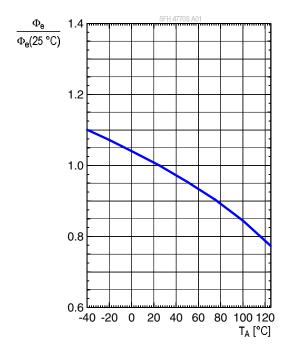
Relative Total Radiant Flux 7), 8)

 Φ_e/Φ_e (1000mA) = f (I_E); single pulse; t_D = 100 µs



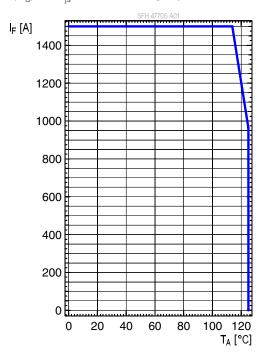
Relative Total Radiant Flux 7)

 $\Phi_e = f(T_A)$; single pulse



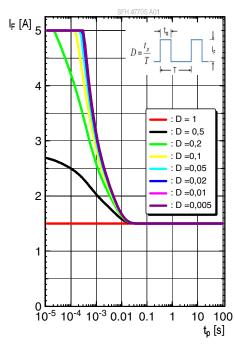
Max. Permissible Forward Current

 $I_{F,max} = f(T_S); Rth_{js} = 9K / W; single pulse$

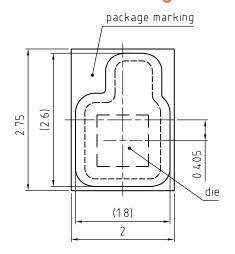


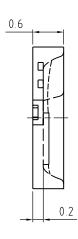
Permissible Pulse Handling Capability

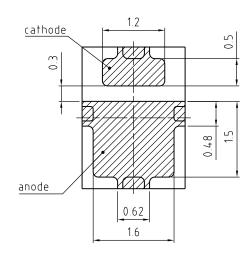
 $I_F = f(t_p)$; duty cycle D = parameter; $T_S = 85$ °C



Dimensional Drawing 9)







General tolerance ±0.1

Lead finish Au

C67062-A0183-A1-02

Further Information:

Approximate Weight: 12.0 mg

Package marking: Cathode

Corrosion test: Class: 3B

Test condition: 40°C / 90 % RH / 15 ppm H₂S / 14 days (stricter than IEC

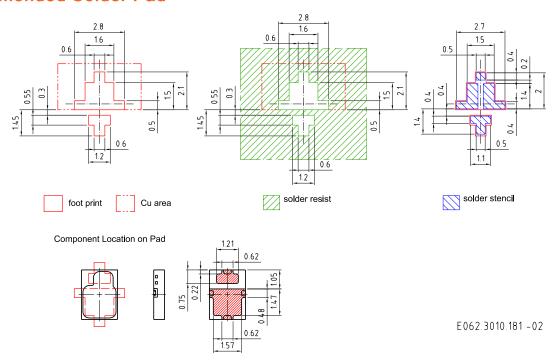
60068-2-43)

ESD advice: The device is protected by ESD device which is connected in parallel to the

Chip.

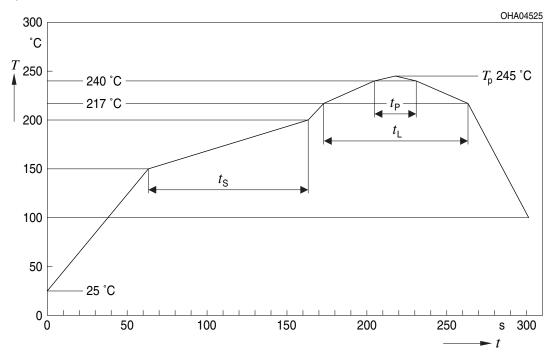


Recommended Solder Pad 9)



Reflow Soldering Profile

Product complies to MSL Level 2 acc. to JEDEC J-STD-020E



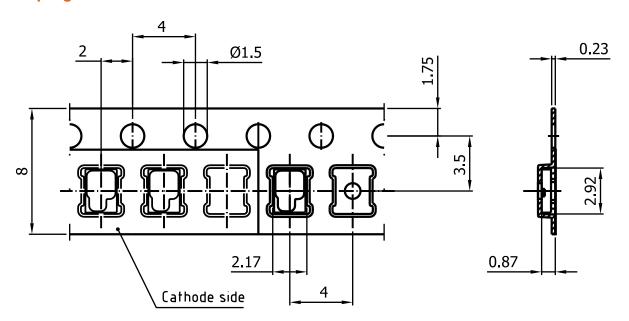
Profile Feature	Symbol	Symbol Pb-Free (SnAgCu) Assembly			Unit
		Minimum	Recommendation	Maximum	
Ramp-up rate to preheat*)	'		2	3	K/s
25 °C to 150 °C					
Time t _s	t _s	60	100	120	S
T_{Smin} to T_{Smax}					
Ramp-up rate to peak*)			2	3	K/s
T_{Smax} to T_{P}					
Liquidus temperature	T_{L}		217		°C
Time above liquidus temperature	$t_{\scriptscriptstyle L}$		80	100	S
Peak temperature	T_{P}		245	260	°C
Time within 5 °C of the specified peak	t _P	10	20	30	S
temperature T _P - 5 K					
Ramp-down rate*			3	6	K/s
T _P to 100 °C					
Time				480	S
25 °C to T _P					

All temperatures refer to the center of the package, measured on the top of the component



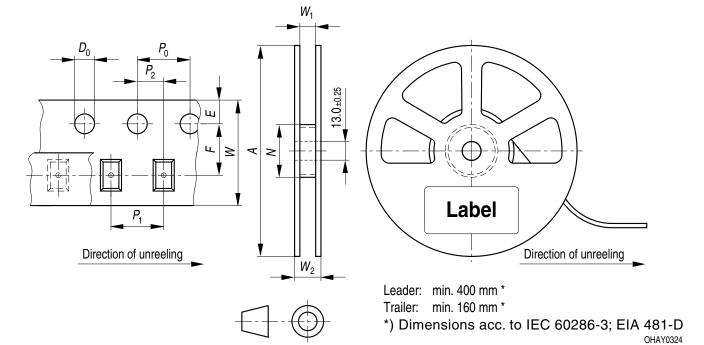
^{*} slope calculation DT/Dt: Dt max. 5 s; fulfillment for the whole T-range

Taping 9)



C67062-A0116-B14-04

Tape and Reel 10)



Reel Dimensions

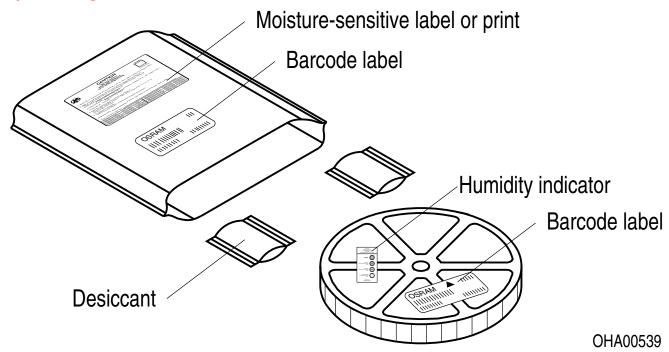
Α	W	N_{\min}	W_1	$W_{2 max}$	Pieces per PU
180 mm	8 + 0.3 / - 0.1 mm	60 mm	8.4 + 2 mm	14.4 mm	2000



Barcode-Product-Label (BPL)



Dry Packing Process and Materials 9)



Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card according JEDEC-STD-033.



Notes

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the device specified in this data sheet falls into the class **exempt group (exposure time 10000 s)**. Under real circumstances (for exposure time, conditions of the eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. When looking at bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this device contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize device exposure to aggressive substances during storage, production, and use. Devices that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

For further application related information please visit www.osram-os.com/appnotes



Disclaimer

Attention please!

The information describes the type of component and shall not be considered as assured characteristics. Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.

For information on the types in question please contact our Sales Organization.

If printed or downloaded, please find the latest version on the OSRAM OS website.

Packing

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

Product and functional safety devices/applications or medical devices/applications

OSRAM OS components are not developed, constructed or tested for the application as safety relevant component or for the application in medical devices.

OSRAM OS products are not qualified at module and system level for such application.

In case buyer – or customer supplied by buyer – considers using OSRAM OS components in product safety devices/applications or medical devices/applications, buyer and/or customer has to inform the local sales partner of OSRAM OS immediately and OSRAM OS and buyer and /or customer will analyze and coordinate the customer-specific request between OSRAM OS and buyer and/or customer.



Glossary

- Total radiant flux: Measured with integrating sphere.
- Brightness: The brightness values are measured with a tolerance of $\pm 11\%$.
- Reverse Operation: Reverse Operation of 10 hours is permissible in total. Continuous reverse operation is not allowed.
- Forward Voltage: The forward voltages are measured with a tolerance of ±0.1 V.
- Radiant intensity: Measured at a solid angle of $\Omega = 0.01 \text{ sr}$
- Thermal resistance: junction soldering point, of the device only, mounted on an ideal heatsink (e.g. metal block)
- Typical Values: Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- ⁸⁾ **Testing temperature:** TA = 25°C (unless otherwise specified)
- Tolerance of Measure: Unless otherwise noted in drawing, tolerances are specified with ±0.1 and dimensions are specified in mm.
- ¹⁰⁾ **Tape and Reel:** All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.



SFH 4770S A01

Revision History			
Version	Date	Change	
1.1	2019-03-26	Description Maximum Ratings Characteristics Electro - Optical Characteristics (Diagrams)	
1.0	2019-09-04	Description Maximum Ratings Characteristics Electro - Optical Characteristics (Diagrams)	
1.1	2019-09-26	Ordering Information Characteristics Electro - Optical Characteristics (Diagrams) Glossary	
1.2	2020-04-02	Characteristics Schematic Transportation Box Dimensions of Transportation Box	



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